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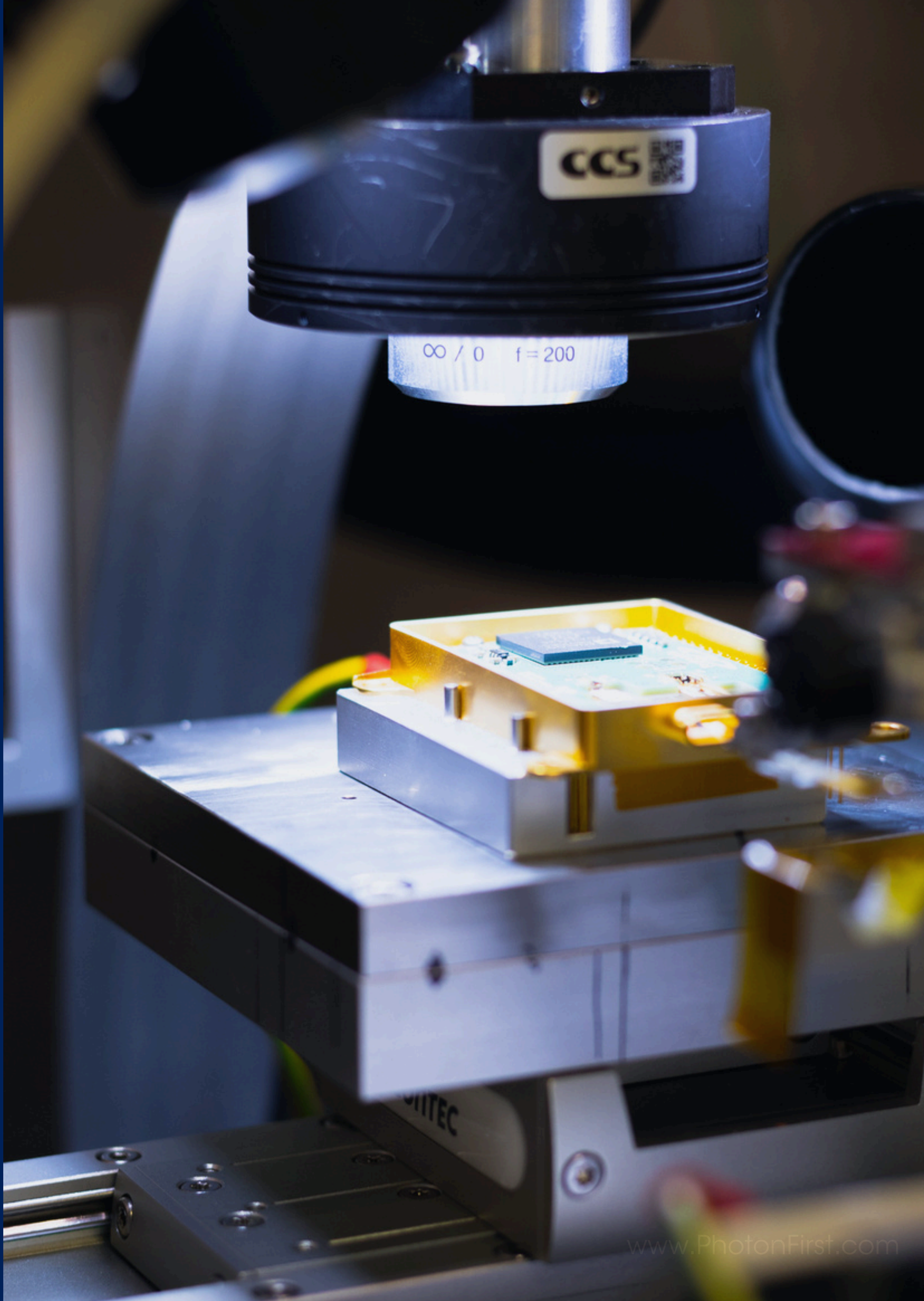
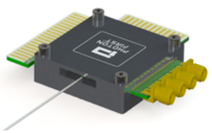
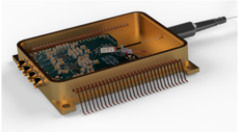
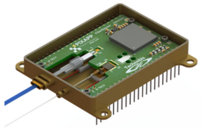
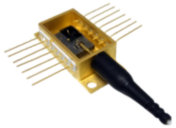
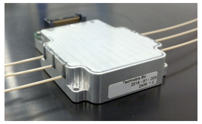
Your **Packaging Partner** to test, create and scale



Overview of packages fit for **applications**

	GP01/02/03	**GB01**	**SIP01**	**BP01**	**XE01**	**CU01..x***
						
Highlights	Design for flexibility	High speed (4xRF)	Opto-electric, multi-chip integration	Standard form factor	Extreme harsh environment	High volume, fit for application
Application	Fast, affordable prototyping	Fast, affordable prototyping	Miniaturizing functional complexity	High volume, single function	Complete system OEM integration	Multi-purpose OEM integration
DC/RF	DC, RF	DC, RF	DC	DC	DC	DC
Fiber#	1, 2, Array	1 (+4 RF)	16	1	1	6
Max Frequency	1GHz	50GHz	20kHz	MHz	100kHz	GHz
Fiber Type	SMF, PM	SMF, PM	SMF, PM	SMF, PM	SMF	SMF, PM
Fiber Coupling	Edge, Array	Edge, Array	Edge, Array	Edge, Single	Edge, Single	Edge, Array
Sealing	Open system	Soldering	Soldering / Epoxy	Soldering	Hermetic	Hermetic
Thermal Control	TEC, NTC	TEC, NTC	TEC, NTC	TEC, NTC	TEC, NTC	TEC, NTC
Dimensions (mm)	83 x 66 x 11.5	52.5 x 55 x 8.5	55 x 60 x 7.5	39 x 35 x 7.8	1151 x 42.8 x 10.6	80 x 50 x 8

*CUxy package types are custom-built and developed fit for application. The specifications can vary significantly for each design

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